


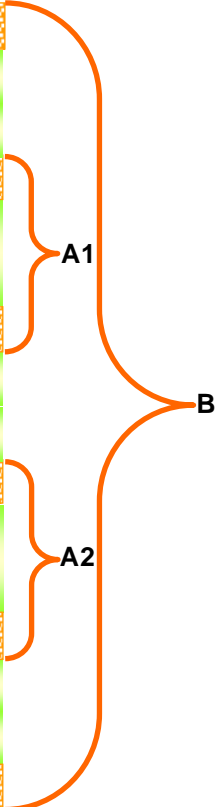

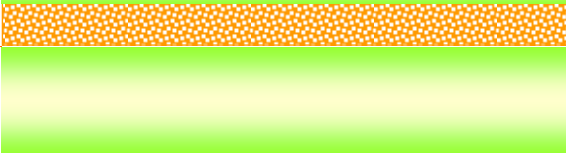
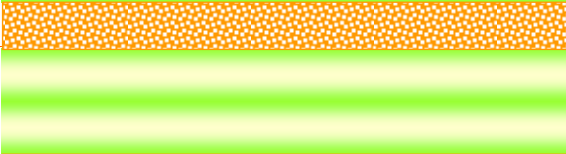









Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

06 167 FR4 55 L41.35 P10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_167_FR4_55_L41.35_p10

Layers	in μ	Material	Build-Up	Assembly
Layer-1	55 μ	Copper		
	100 μ	Prepreg	(100 μ PrePreg-Type: 2125)	
	100 μ	Prepreg		
Layer-2	35 μ	Copper		
	410 μ	L-FR4		
Layer-3	35 μ	Copper		
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-4	35 μ	Copper		
	410 μ	L-FR4		
Layer-5	35 μ	Copper		
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-99	55 μ	Copper		

© Copyright by Printed Circuit Boards GmbH